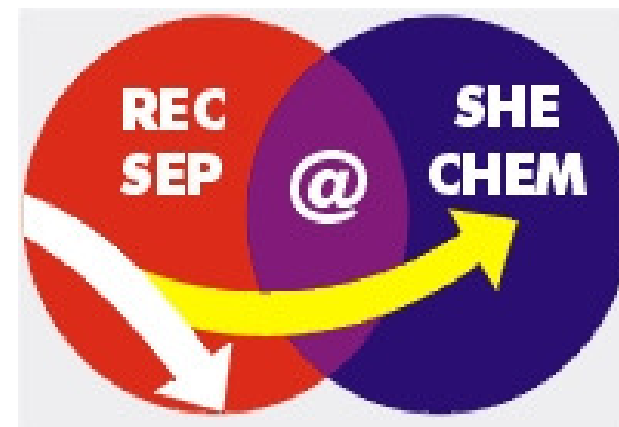


TASCA Target Group Status Report

K. Eberhardt for the TASCA Target Group

- **New Target Station**
- **In-beam Performance of UF_4 -Targets**
- **New Cell for Electrodeposition**
- **Outlook**



Target Group Members



D. Ackermann, W. Bröchle, E. Jäger, B. Kindler, B. Lommel,
M. Schädel, E. Schimpf



A. Türler, A. Yakushev

A. Semchenkov



H.-J. Maier, J. Szerypo



Berkeley Lab

K. Gregorich, R. Sudowe



K. Eberhardt, J.V. Kratz, D. Liebe, P. Thörle

New members are always invited to join the group!



Target Group Meetings

Workshop on Recoil Separator for Superheavy Element Chemistry
March 20 - 21, 2002, GSI, Darmstadt, Germany

BGS / ChemSep Workshop
LBNL/Berkeley, November 21, 2003

3rd Workshop on Recoil Separator for Superheavy Element Chemistry (TASCA 04): August 27, 2004, GSI, Darmstadt, Germany

Working groups started on specific tasks \Rightarrow TASCA Target Group:

- Targets (preparation, rotation, safety, control, cooling),

- Window

Dec. 10, 2004:

1st TASCA Target Group Meeting



- Collimator

March 2, 2005:

2nd TASCA Target Group Meeting



July 20, 2005:

3rd TASCA Target Group Meeting

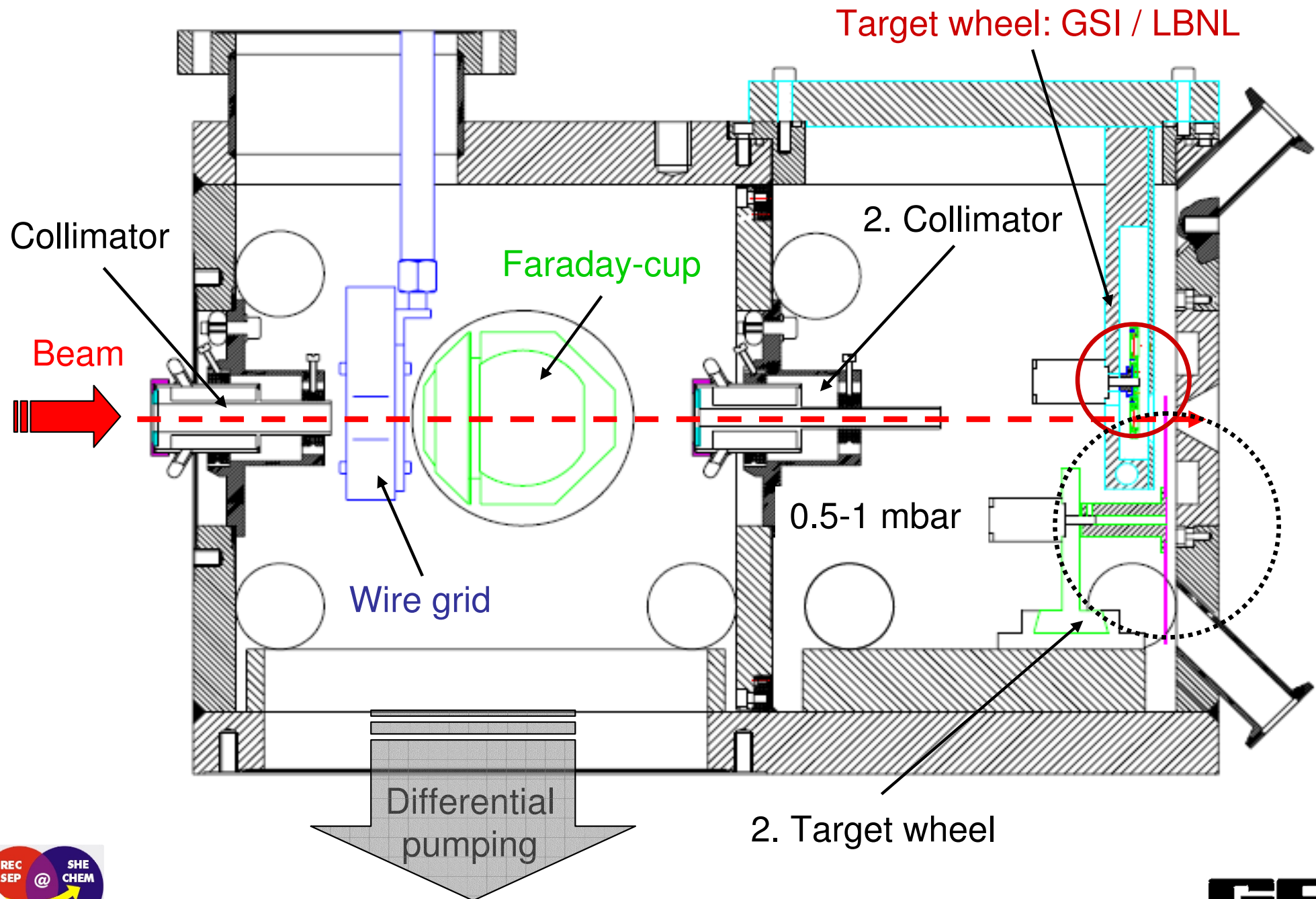


4th Workshop on Recoil Separator for Superheavy Element Chemistry (TASCA05) October 6, 2005, Oslo, Norway

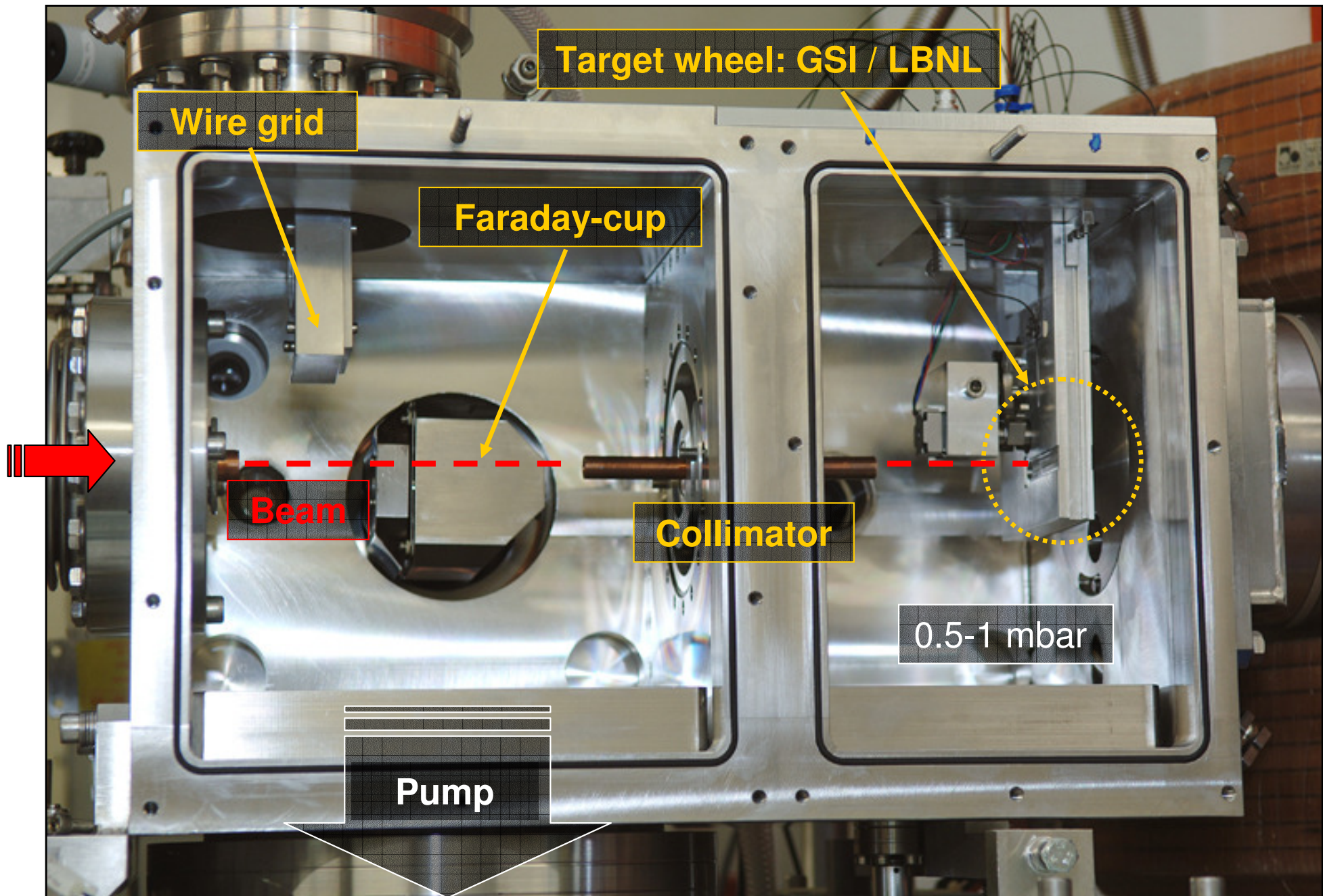
TASCA Target Group Meeting/TASCA Commissioning Kick-off Meeting
May 15th, 2006 @ GSI



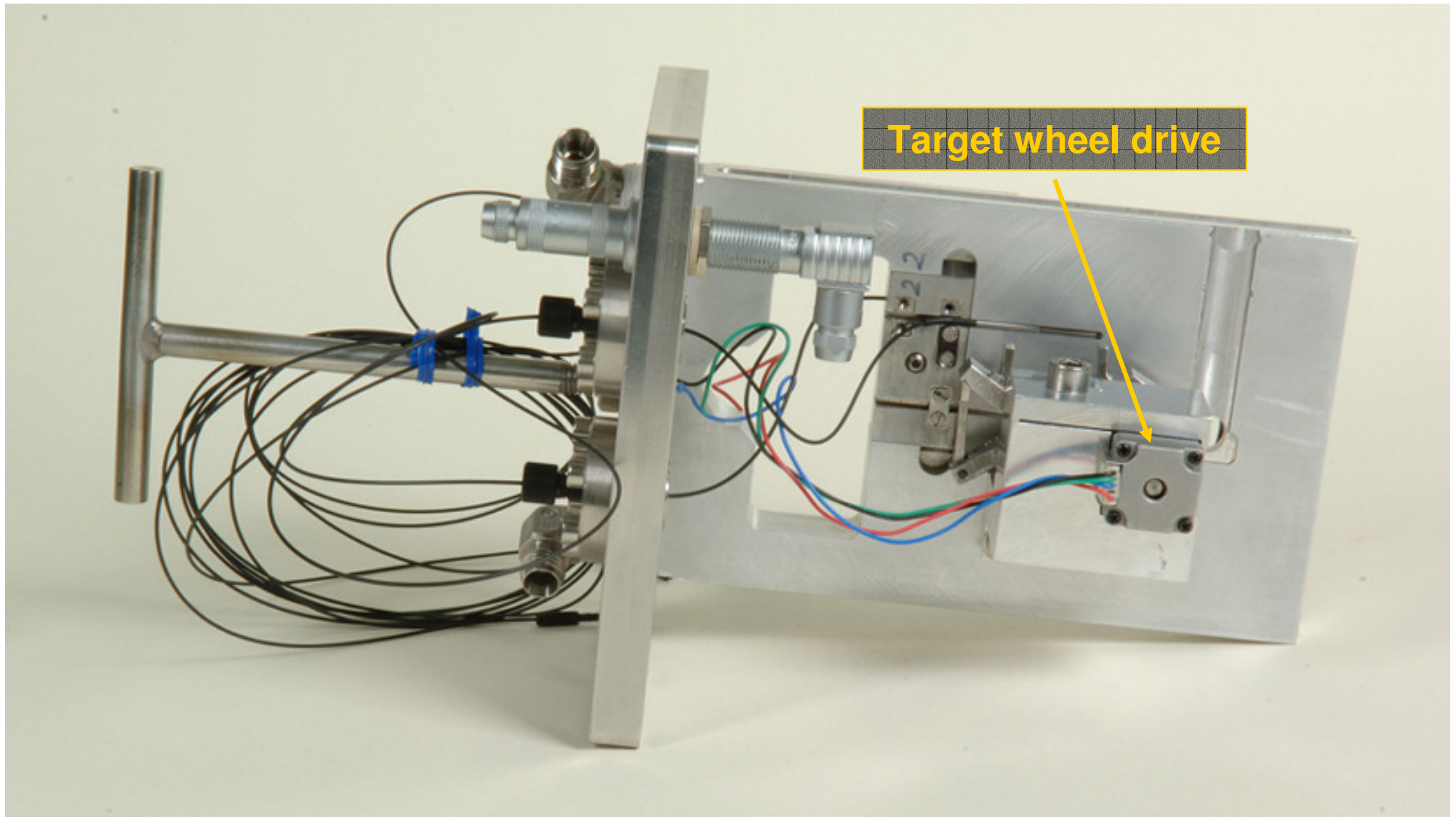
New Target Station for TASCA



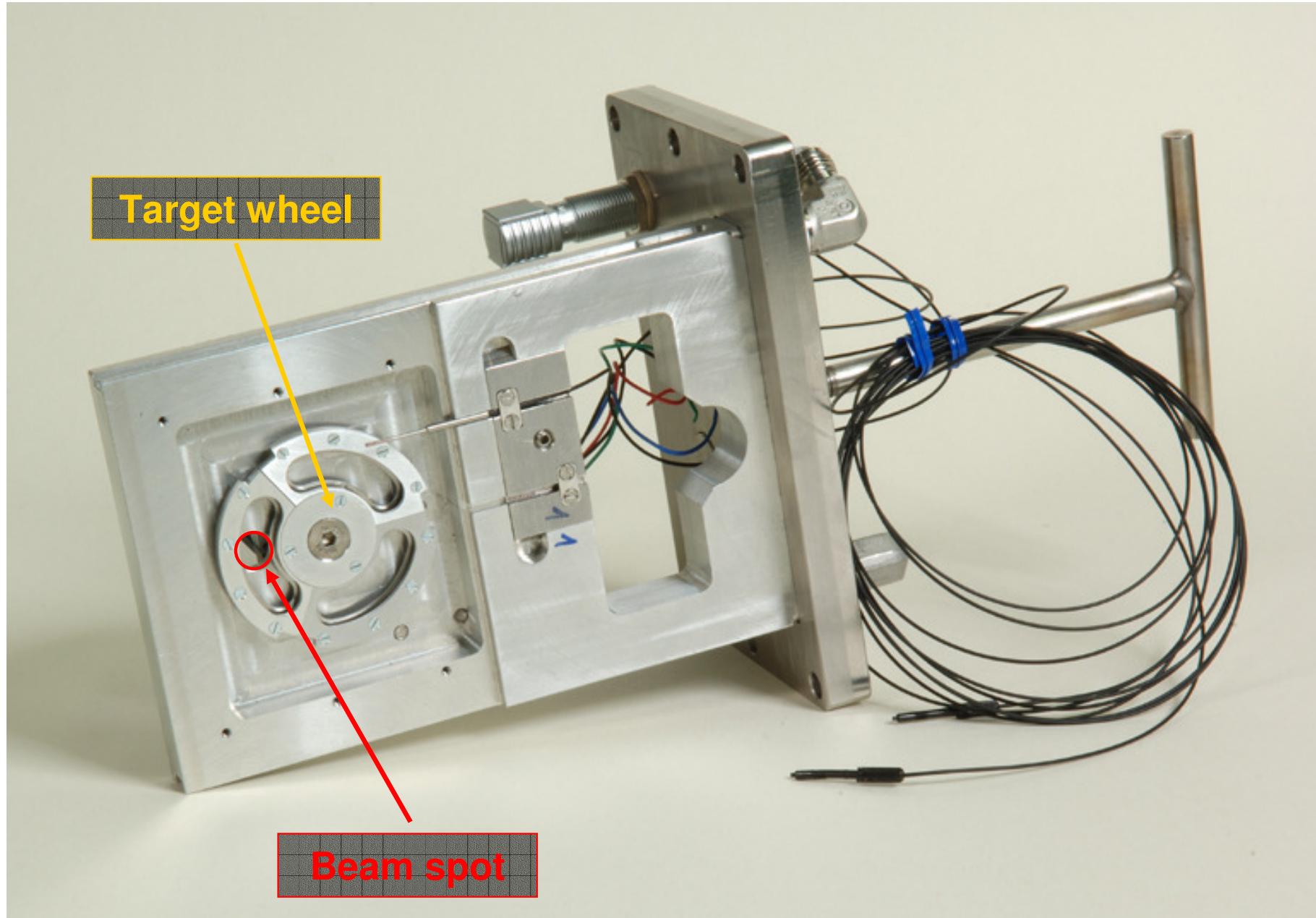
New Target Station for TASCA



New Target Station for TASCA

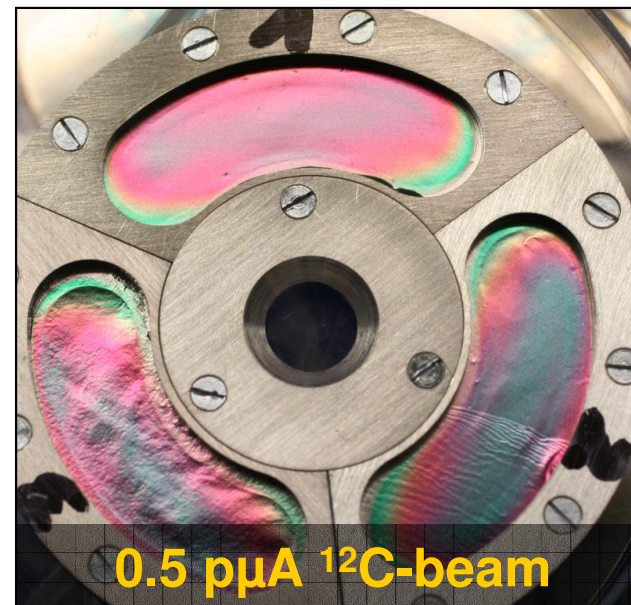


New Target Station for TASCA



In-beam Performance of UF₄-Targets / ¹²C-beam

- Frames out of AlMg3, thickness: 0.5 mm
- Cold rolled foils out of Al 2.25 μm, 4.6 μm, 6.4 μm, 10 μm (Goodfellow + WANIT)
- backing + thermal evaporation + covering layer
- Al + UF₄ + C
- 2 - 10 μm 350 – 450 μg/cm² + ~ 10 μg/cm²
- (according to U)



→ Target performed well.
No damage, no holes

In-beam Performance of UF₄-Targets / ²⁶Mg-beam

- Cold rolled Al foils: different thicknesses and fabricates
- Cold rolled Al + evaporated UF₄ + C covering layer



1.0 pμA ²⁶Mg-beam

- Target unstable in beam
- Search for alternative backing materials

Thermal Expansion (TR) of Backing and Target Materials

Thermal expansion coefficient at room temperature
given in $[\mu\text{m}/(\text{m}\cdot\text{K})] = 10^{-6} [1/\text{K}]$

Backing materials

Target materials

C = 7.1

U = 13.9

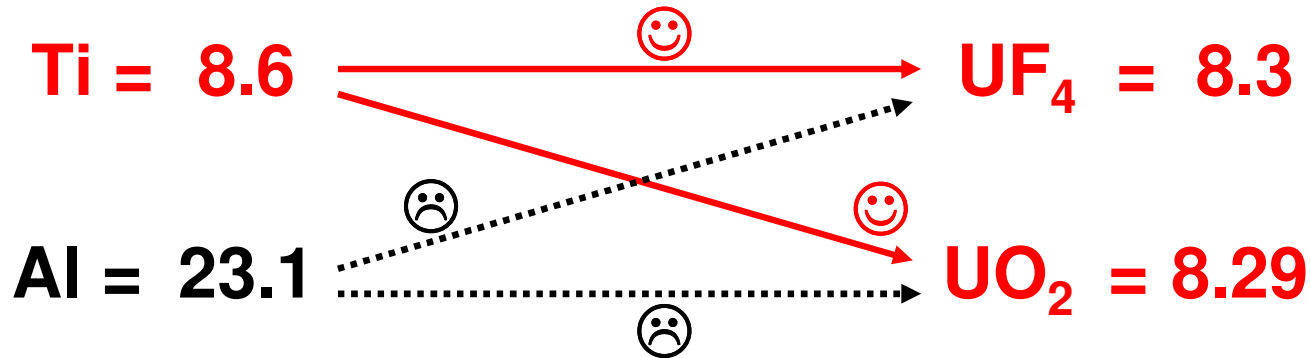
Ti = 8.6

UF₄ = 8.3

Al = 23.1

UO₂ = 8.29

UC = 10.0



Handbook of Physics and Chemistry,
85th edition

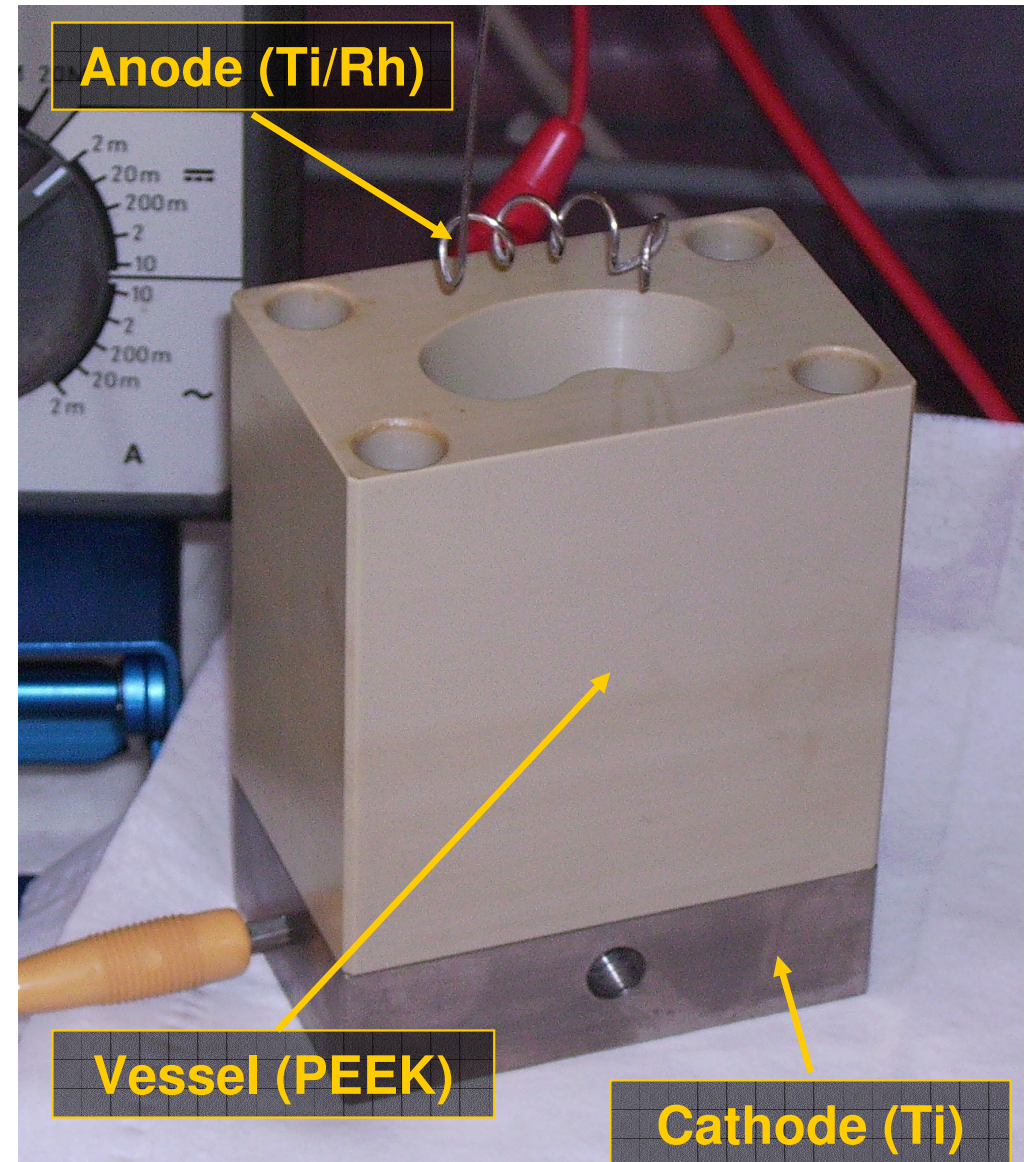
Gmelin, Uranium compounds



Target Preparation by Electrodeposition (Molecular Plating)

Old Plating Cell

- **Cathode: Ti-block, cooled in ice/water bath**
- **Anode: Coiled Pt (Rh) wire causes strong inhomogeneity in electrical field**
- **Vessel: PEEK containing ca. 12 ml of organic solvent. No effective cooling of plating solution possible**

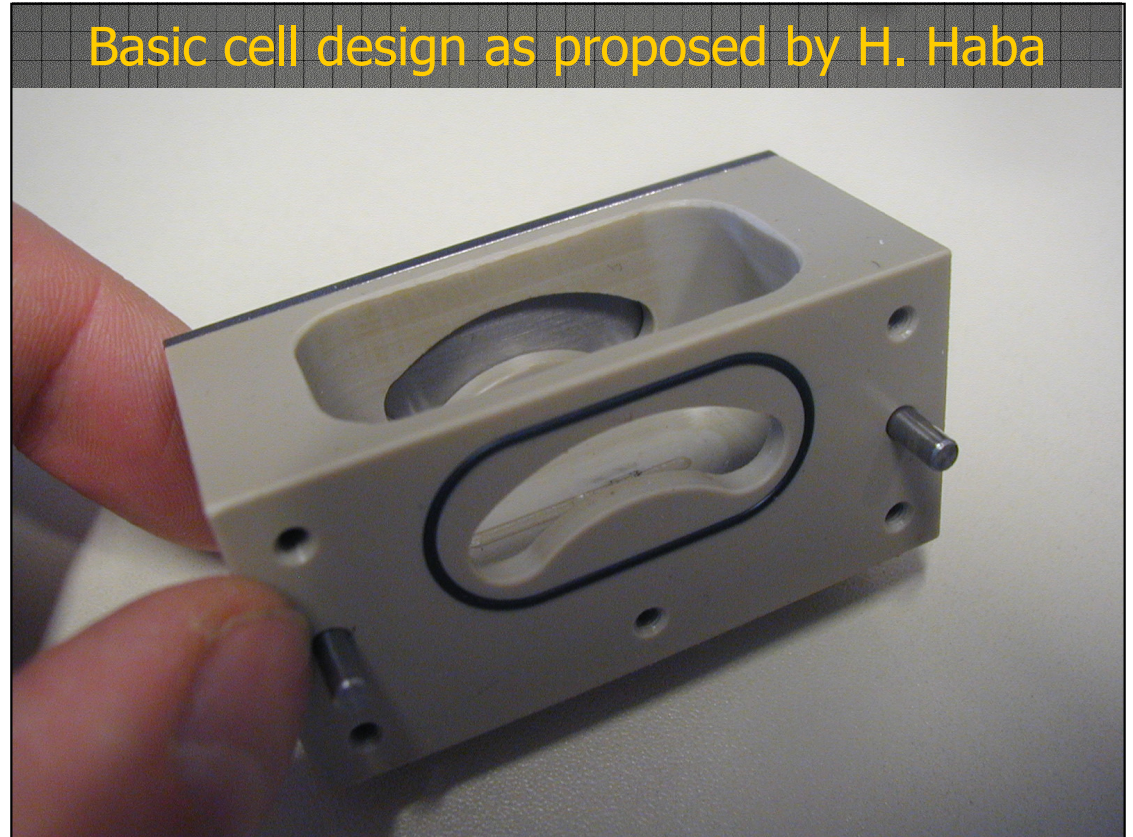


New Cell for Molecular Plating

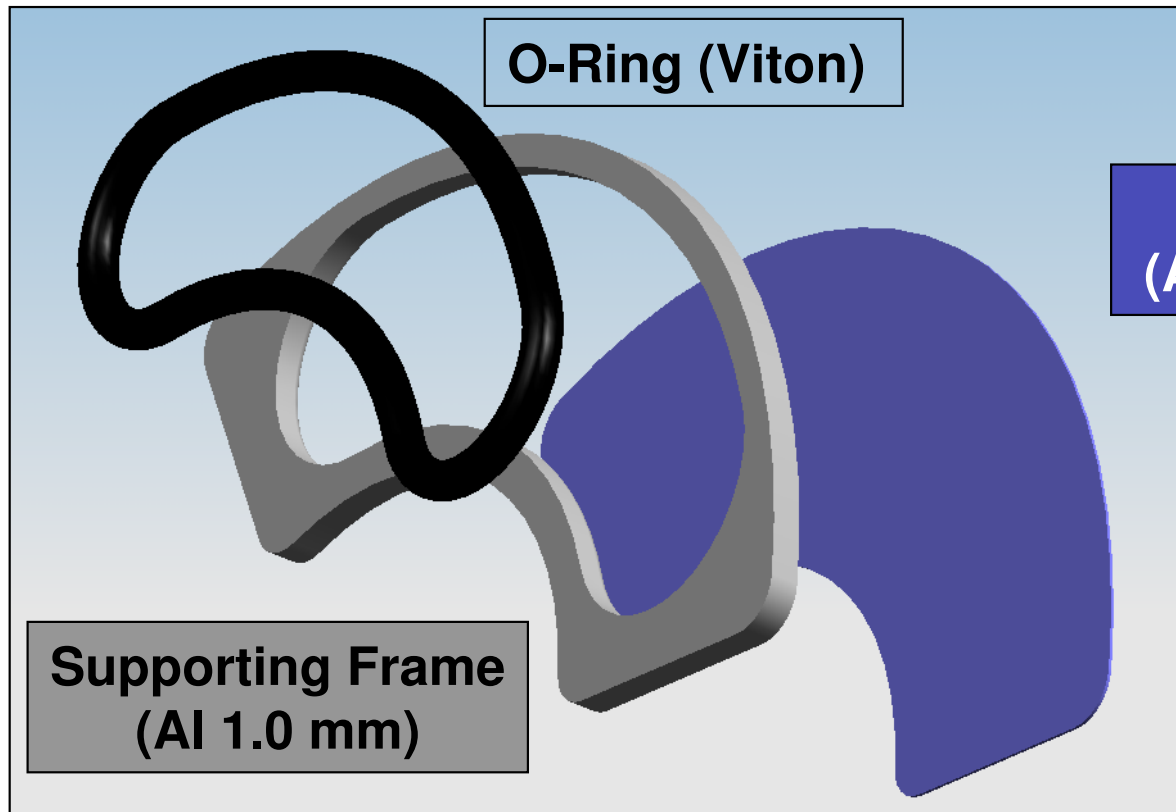
New Plating Cell

- Material: PEEK
- Volume: about 16 ml
- Anode geometry corresponds to cathode (target) geometry.
Electrical field homogenous
- **Stirring** of solution during deposition possible
- Effective **cooling** and **temperature control** during deposition

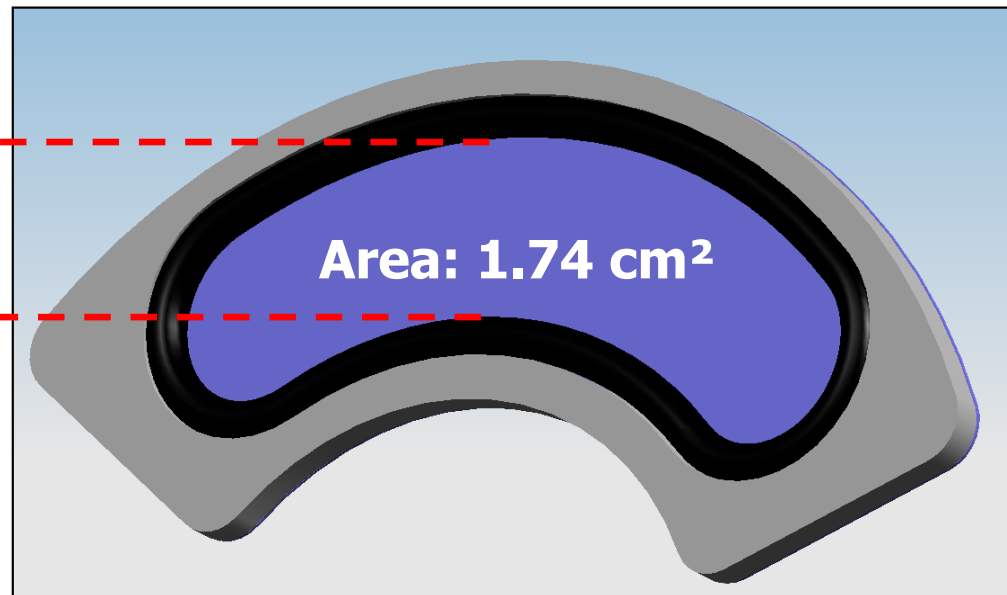
Basic cell design as proposed by H. Haba



New Cell for Molecular Plating

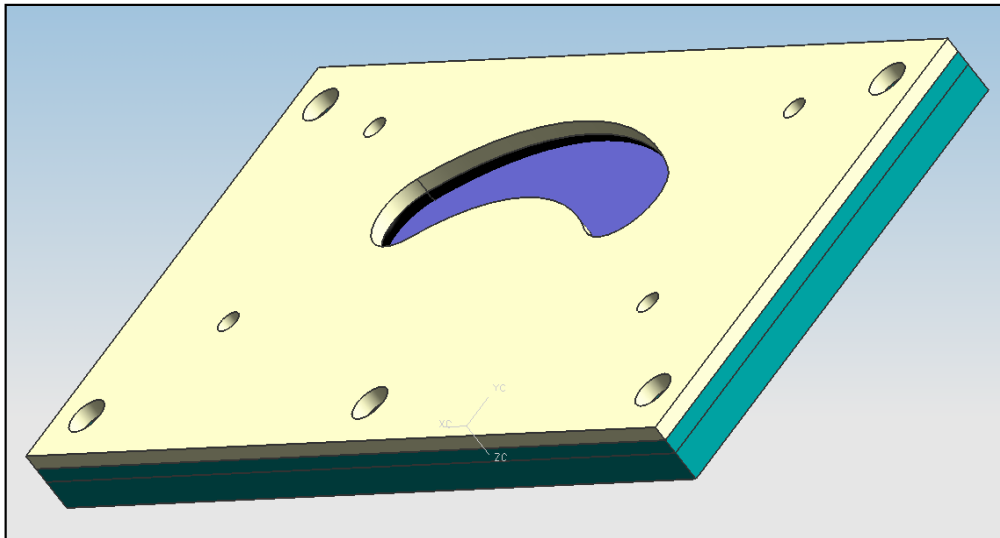
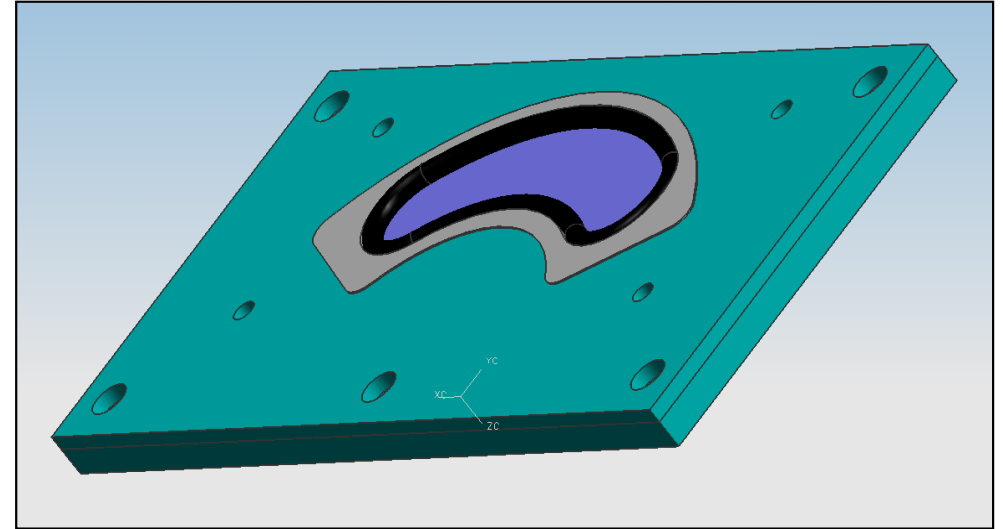
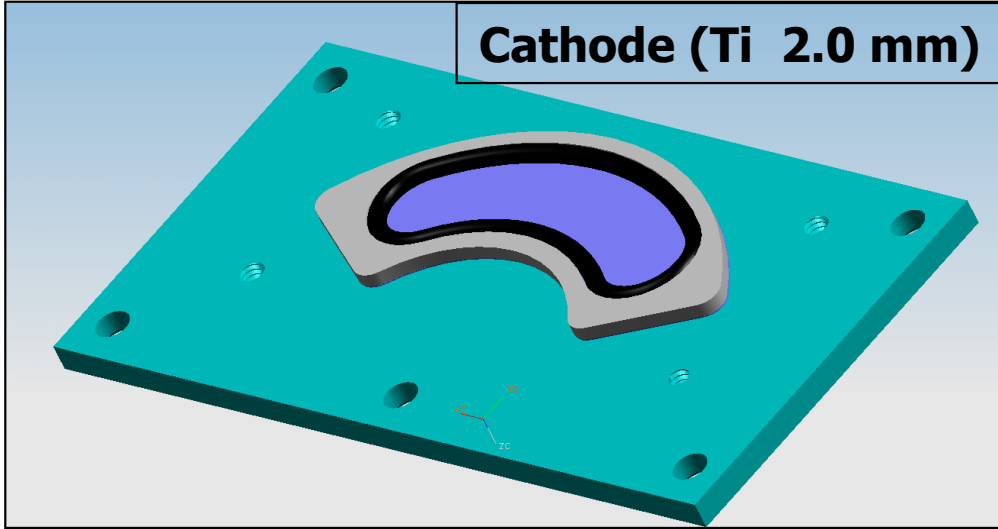


6 mm

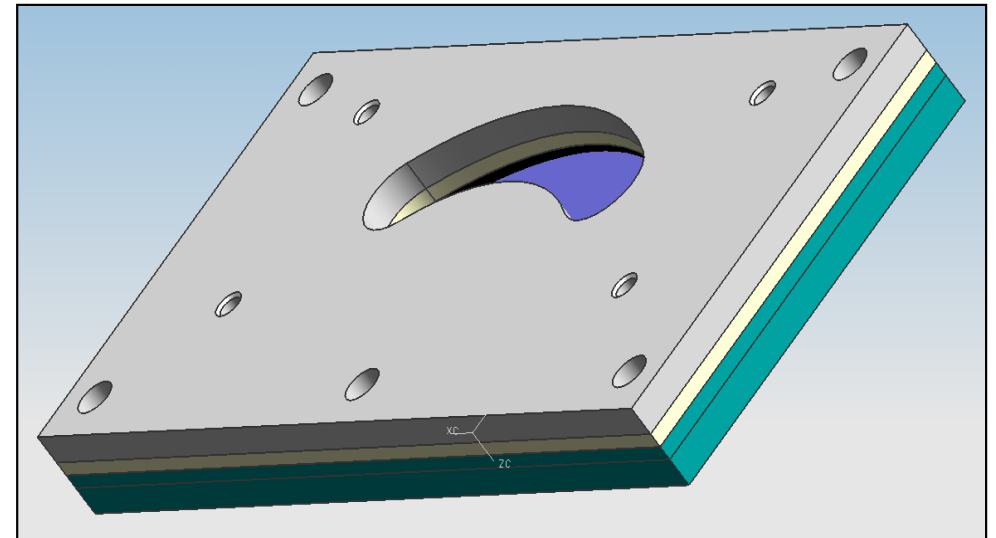


New Cell for Molecular Plating

Cathode (Ti 2.0 mm)



Silicon plate(1.0 mm)

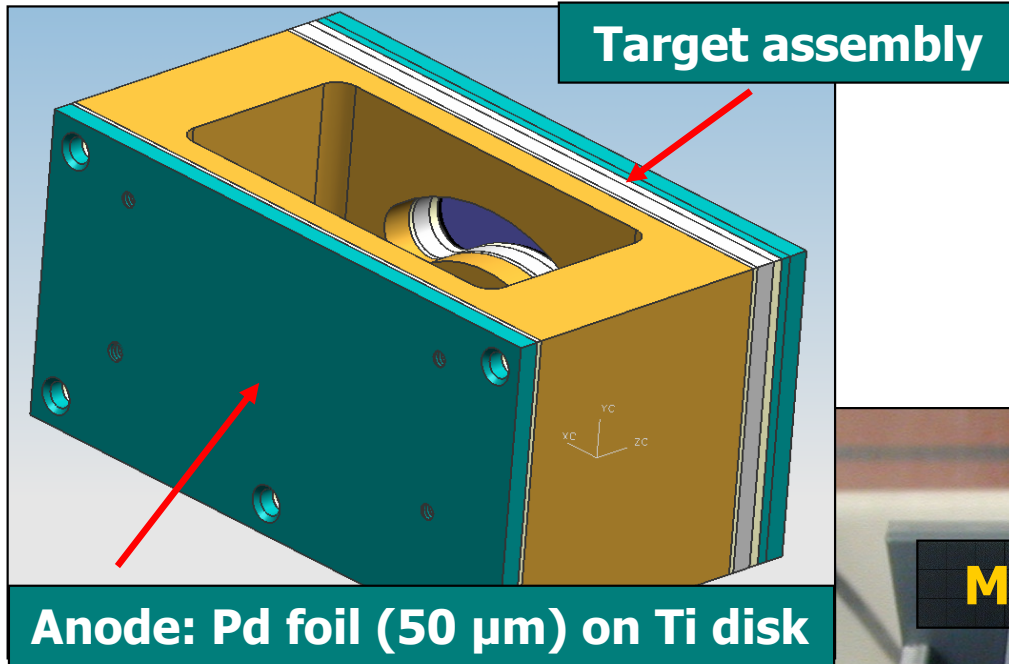


Plexiglas plate (2.0 mm)

→ Easy and safe target handling

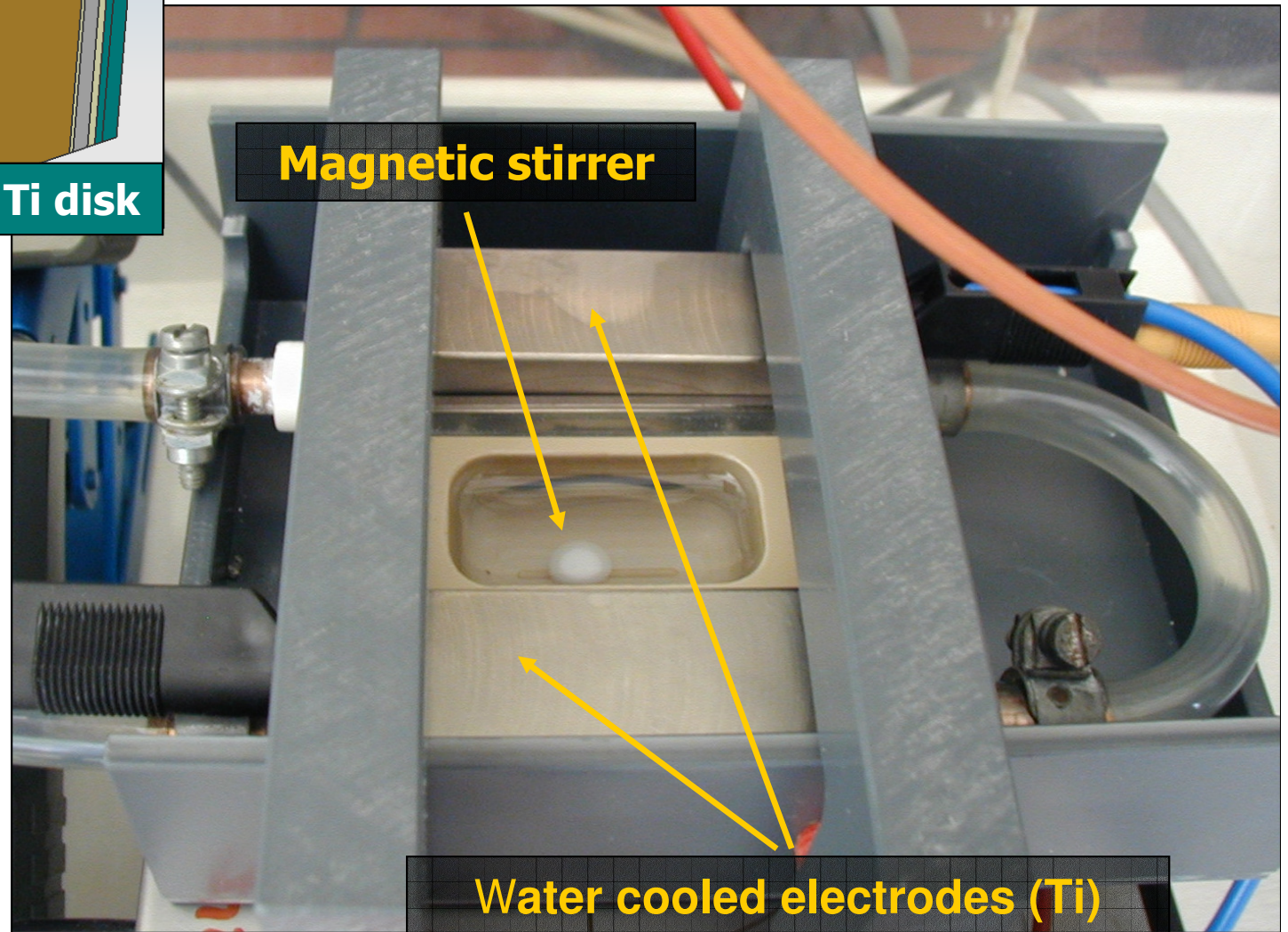
New Cell for Molecular Plating

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MAINZ

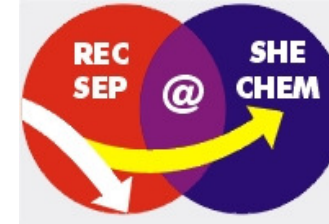
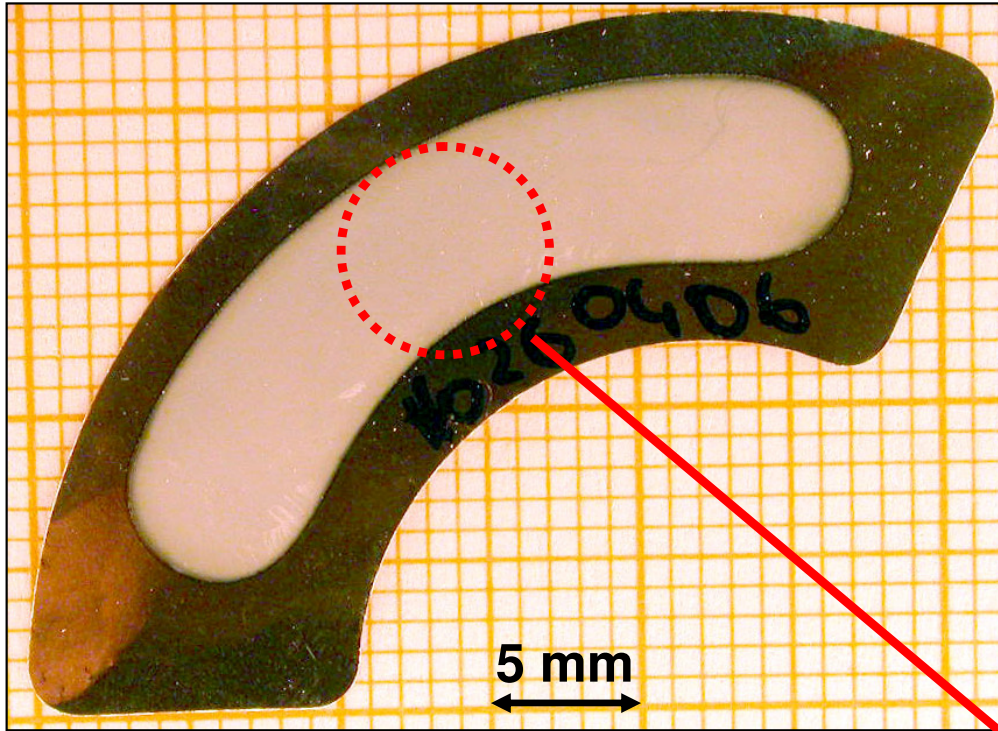


Cooling water →

← Cooling water



Ho- and Gd-targets for TASCA Commissioning



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UNIVERSITÄT
MAINZ

Ho ($500 \mu\text{g}/\text{cm}^2$) on Ti ($5 \mu\text{m}$)

**Plating solution: 1.0 mg Ho/Gd in
16 ml 2-butanol**

Plating Voltage: 150 V

Plating time: 5 h

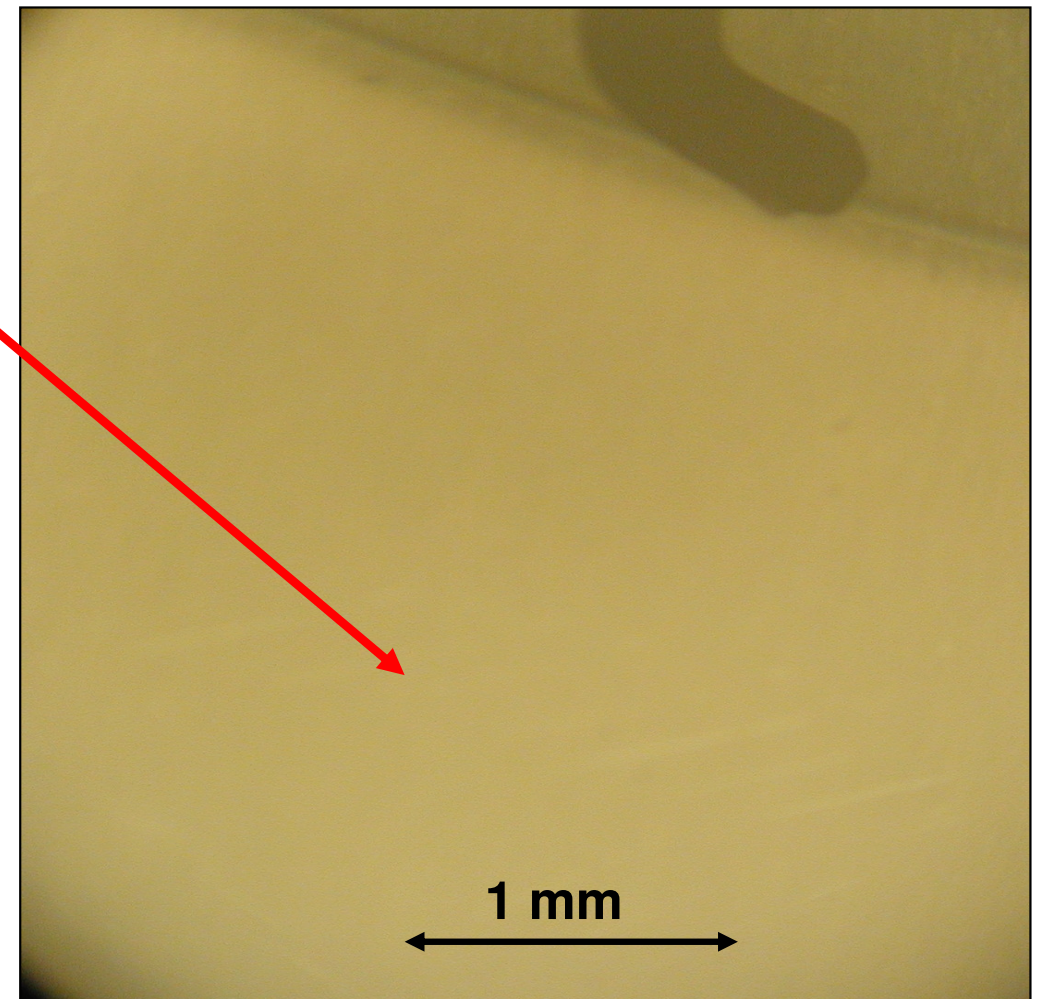
Temperature: 18 °C

Target Area: 1.74 cm²

Deposition Yield: > 90 %

Target Thickness: > 500 $\mu\text{g}/\text{cm}^2$

⇒ 9 targets (4x Ho and 5x Gd)



Outlook



Isotopic analysis of the actinide compounds used for target production by means of ICP-MS



Optimize plating conditions for Th, U, Pu, Cm + Lanthanides. Imaging of U- and Th-targets before and after irradiation using autoradiography and TEM (at GSI)



Test and optimization of rotating target station for TASCA/BGS



Production of thin Al backing foils. Preparation of U/UF₄ targets (Al- /Ti- / C-backings). Test of in-beam target performance



U/Th-Oxide targets on different backings including carbon as backing material.

